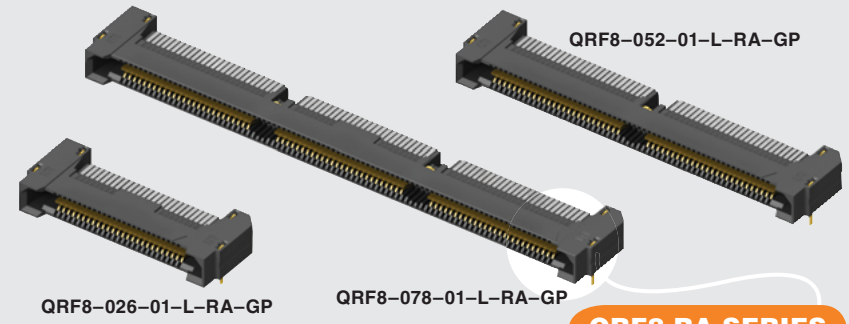


(0,80 mm) .0315"

QRF8-RA SERIES

RIGHT ANGLE GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QRF8-RA

Insulator Material:
Black LCP
Contact Material:
BeCu
Ground Plane Material:
Phosphor Bronze
Plating:
Au or Sn over
50µ" (1,27 µm) Ni
Current Rating (QRF8-RA/QRM8):
Contact:
2.2 A per pin
(1 pin powered per row)
Ground Plane:
8.6 A per ground plane
(1 ground plane powered)
Operating Temp Range:
-55°C to +125°C
Voltage Rating:
230 VAC / 325 VDC
RoHS Compliant:
Yes

Processing:

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0,10 mm) .004" max (026-052)
(0,15 mm) .006" max (078)

RECOGNITIONS

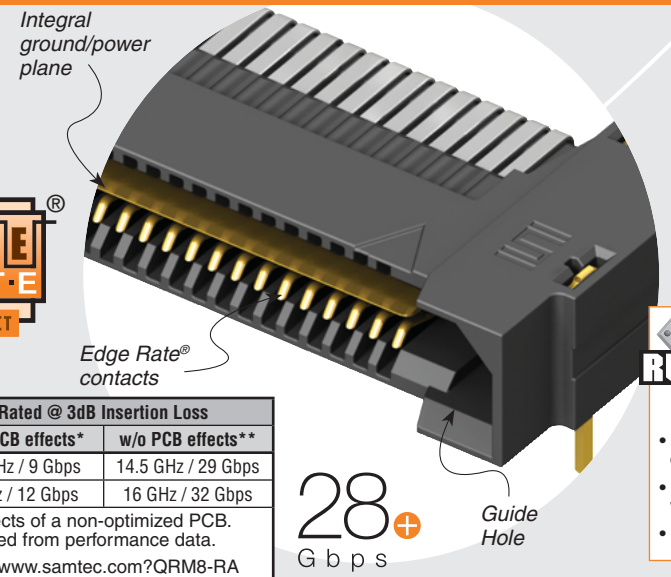
For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

ALSO AVAILABLE
(MOQ Required)

- Other platings
  Contact Samtec.

Board Mates:
QRM8 (–GP required)



EDGE RATE® CONTACT

28+ Gbps

RUGGEDIZED by SAMTEC

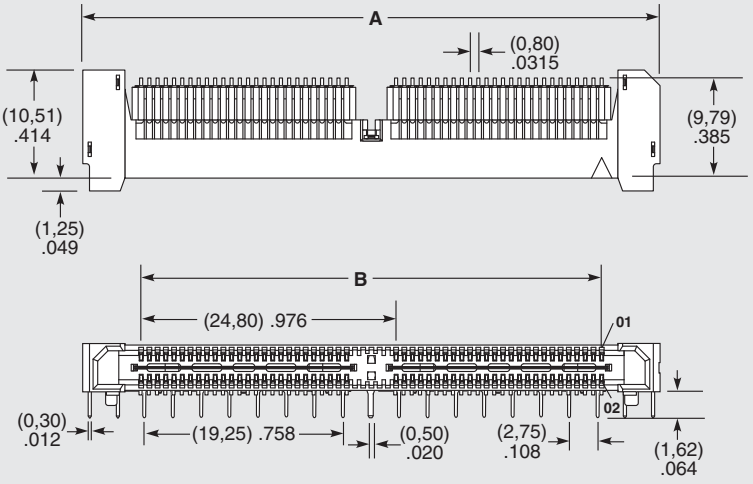
- Edge Rate® contacts
- Increased contact wipe
- Integral guide post

QRM8-RA/QRF8-RA	Rated @ 3dB Insertion Loss	
	with PCB effects*	w/o PCB effects**
Single-Ended Signaling	4.5 GHz / 9 Gbps	14.5 GHz / 29 Gbps
Differential Pair Signaling	6 GHz / 12 Gbps	16 GHz / 32 Gbps

*Performance data includes effects of a non-optimized PCB.
**Test board losses de-embedded from performance data.

Complete test data available at www.samtec.com?QRM8-RA or contact sig@samtec.com

QRF8	–	POSITIONS PER ROW	–	01	–	PLATING OPTION	–	RA	–	GP	–	OPTION
		–026, –052, –078 (52 total positions per bank)				–L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail				–GP = Guide Post (Requires –GP on mating connector)		–K = (7,00 mm) .275" DIA Polyimide film Pick & Place Pad (–052 only) –TR = Tape & Reel (–026, –052 only)



POSITIONS PER ROW	A	B
–026	(31,35) 1.234	(20,00) .787
–052	(56,15) 2.211	(44,80) 1.764
–078	(80,95) 3.187	(69,60) 2.740

Note:
Patented

Note:
For –GP (Guide Post option) to –GP (Guide Post option) mating.

Note:
Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.